

Call for Papers

International MEMS/MST Industry Forum

18-19 October, Dresden, Germany
In conjunction with SEMICON Europa 2010

“MEMS Goes Everywhere!”

Semiconductor Equipment and Materials International (SEMI) invites MEMS/MST professionals to submit abstracts for the conference, which will be held in conjunction with SEMICON Europa 19-21 October 2010 in Dresden, Germany.

Micro systems technologies play a very major role in today's and future electronics market development. The 'consumerization' of electronics products makes pressure on components cost relentless; the 'cost of solution' must be rigorously driven down to match market requirements of low-cost / high-tech commodity electronics.

How to successfully manage in an environment with distributed operations, while best system know-how and ever shorter time-to-revenue cycles are essential? Which control systems and methodologies for low cost testing, steep learn curves and quality assurance need to be in place? How to develop, manufacture and cost/efficiently integrate complex heterogeneous systems? What are the most recent developments in MEMS enabled products: where lay the challenges and opportunities? What are most interesting new applications and use-cases, driving new technologies and providing for technology line utilization?

Semiconductor Equipment and Materials International (SEMI) invites MEMS/MST professionals to submit abstracts to the International MEMS/MST Industry Forum, which will be held in conjunction with SEMICON Europa 2010 in Dresden, Germany.

Presentations on original, non-commercial works describing recent developments are welcome:

Session 1: MEMS applications *Emerging applications which are driving new MEMS technologies*

- Automotive
- Biomedical / life sciences applications
- Optical microsystems
- RF components
- MEMS for mobile phones / gaming
- MEMS for energy saving and harvesting

Session 2: Manufacturing Strategies and Challenges *Viable production concepts for MEMS products*

- IDM versus foundries versus MEMS Production Embedded in IC manufacturing
- Leverage of standardization in MEMS technologies
- Strategies for medium volume, high added volume and emerging products
- Wafer-level testing and new packaging technologies
- High throughput testing of MEMS devices
- Integration of MEMS into monolithic circuits

Session 3: MEMS Technologies Process *New materials and processes for MEMS, front-end, back-end and testing*

- 3D and TSV processes
- Sealing and capping technologies
- Chip and WLP technologies for MEMS
- Cost efficient testing

Session 4: MEMS Market Review - *MEMS Goes Everywhere!*

- MEMS application markets, forecasts and outlook

Instructions to submit an abstract – Submit the following information in an e-mail:

- Specify which session 1, 2, 3 or 4 your presentation falls in to
- Presentation title
- Abstract of 200-400 words (descriptive paragraph identifying issue addressed and solution)
- Short biography of the author and picture
- Author contact details (Job title, company, address, telephone/e-mail)
- Contact person details i.e. Personal Assistant (Job title, company, address, telephone/e-mail)
- Indicate in subject box of e-mail: MEMS/MST Call for papers

Please submit ALL the above information in one e-mail by 30 April 2010 (extended deadline) to euromicro@semi.org

Your presentation will not be included in the review process unless the information is complete.

Evaluation criteria include significance, usefulness for the manufacturing world and clarity and accuracy as a paper. Abstracts will be peer-reviewed and selected relative to the points above. We encourage application related presentations, i.e. on joint projects between users and suppliers. Papers are to be non-commercial and focus on the technical/economical merits of a process rather than the individual company's product benefits.

Selected presenters will be notified by 28 May 2010.

Program Committee: Gerhard Lammel, Bosch Sensortec (chairman), Felix Rudolf, Colibrys (vice-chairman); Christian Schaefer, PVA Tepla; Erik Jung, Fraunhofer IZM; Jérémie Bouchaud, iSuppli; Jean-Christophe Eloy, Yole Développement; Peter ten Berge, ASML; Uwe Behringer, UBC Microelectronics; Uwe Schwarz, X-Fab; Mikko Montonen, Okmetic; Markus Gabriel, Suss MicroTec; Thomas Gessner, FhG IZM/ENAS, Paul Lindner, EVG

For information on SEMICON Europa 2010, please visit www.semiconeuropa.org or contact Carlos Lee, per email clee@semi.org or per telephone: +32.2.289.64.90